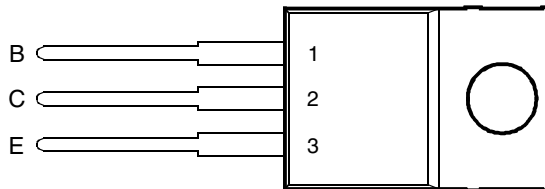




- Designed for Complementary Use with BDX34, BDX34A, BDX34B, BDX34C and BDX34D
- 70 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3V, 3 A

TO-220 PACKAGE
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	BDX33	V_{CBO}	45	V
	BDX33A		60	
	BDX33B		80	
	BDX33C		100	
	BDX33D		120	
Collector-emitter voltage ($I_B = 0$)	BDX33	V_{CEO}	45	V
	BDX33A		60	
	BDX33B		80	
	BDX33C		100	
	BDX33D		120	
Emitter-base voltage		V_{EBO}	5	V
Continuous collector current		I_C	10	A
Continuous base current		I_B	0.3	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)		P_{tot}	70	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 2)		P_{tot}	2	W
Operating free air temperature range		T_J	-65 to +150	°C
Storage temperature range		T_{stg}	-65 to +150	°C
Operating free-air temperature range		T_A	-65 to +150	°C

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.
2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

PRODUCT INFORMATION

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
$V_{(BR)CEO}$ Collector-emitter breakdown voltage	$I_C = 100 \text{ mA}$	$I_B = 0$	(see Note 3)	BDX33	45		V
				BDX33A	60		
				BDX33B	80		
				BDX33C	100		
				BDX33D	120		
I_{CEO} Collector-emitter cut-off current	$V_{CE} = 30 \text{ V}$	$I_B = 0$	$T_C = 100^\circ\text{C}$	BDX33		0.5	mA
				BDX33A		0.5	
				BDX33B		0.5	
				BDX33C		0.5	
				BDX33D		0.5	
				BDX33		10	
				BDX33A		10	
				BDX33B		10	
				BDX33C		10	
				BDX33D		10	
I_{CBO} Collector cut-off current	$V_{CB} = 45 \text{ V}$	$I_E = 0$	$T_C = 100^\circ\text{C}$	BDX33		1	mA
				BDX33A		1	
				BDX33B		1	
				BDX33C		1	
				BDX33D		1	
				BDX33		5	
				BDX33A		5	
				BDX33B		5	
				BDX33C		5	
				BDX33D		5	
I_{EBO} Emitter cut-off current	$V_{EB} = 5 \text{ V}$	$I_C = 0$				10	mA
h_{FE} Forward current transfer ratio	$V_{CE} = 3 \text{ V}$	$I_C = 4 \text{ A}$	(see Notes 3 and 4)	BDX33	750		
				BDX33A	750		
				BDX33B	750		
				BDX33C	750		
				BDX33D	750		
$V_{BE(on)}$ Base-emitter voltage	$V_{CE} = 3 \text{ V}$	$I_C = 4 \text{ A}$	(see Notes 3 and 4)	BDX33		2.5	V
				BDX33A		2.5	
				BDX33B		2.5	
				BDX33C		2.5	
				BDX33D		2.5	
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 8 \text{ mA}$	$I_C = 4 \text{ A}$	(see Notes 3 and 4)	BDX33		2.5	V
				BDX33A		2.5	
				BDX33B		2.5	
				BDX33C		2.5	
				BDX33D		2.5	
V_{EC} Parallel diode forward voltage	$I_E = 8 \text{ A}$	$I_B = 0$				4	V

NOTES: 3. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

PRODUCT INFORMATION



thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.78	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t_{on} Turn-on time	$I_C = 3\text{ A}$	$I_{B(on)} = 12\text{ mA}$	$I_{B(off)} = -12\text{ mA}$		1		μs
t_{off} Turn-off time	$V_{BE(off)} = -3.5\text{ V}$	$R_L = 10\ \Omega$	$t_p = 20\ \mu\text{s}, \text{dc} \leq 2\%$		5		μs

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PRODUCT INFORMATION

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN
VS
COLLECTOR CURRENT

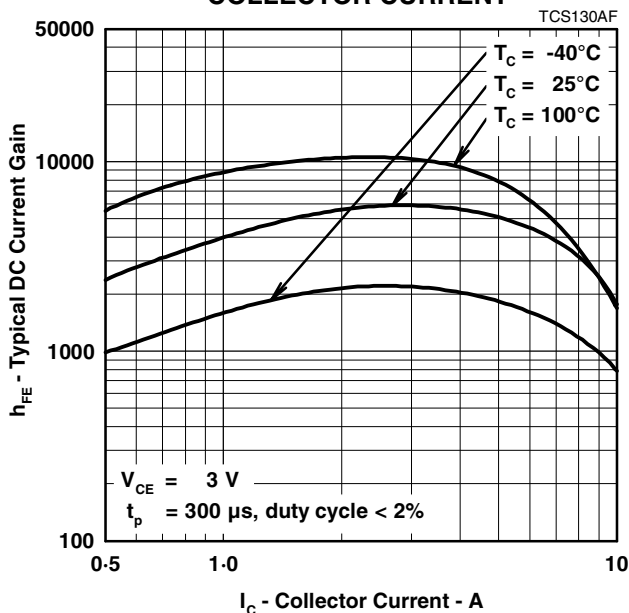


Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE
VS
COLLECTOR CURRENT

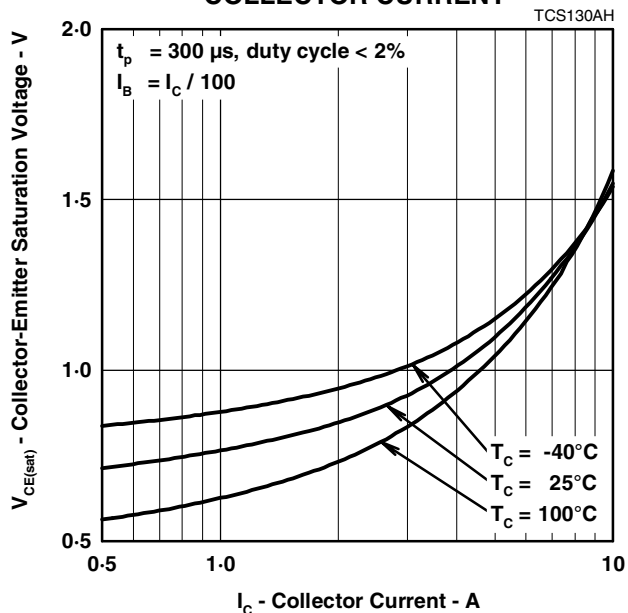


Figure 2.

BASE-EMITTER SATURATION VOLTAGE
VS
COLLECTOR CURRENT

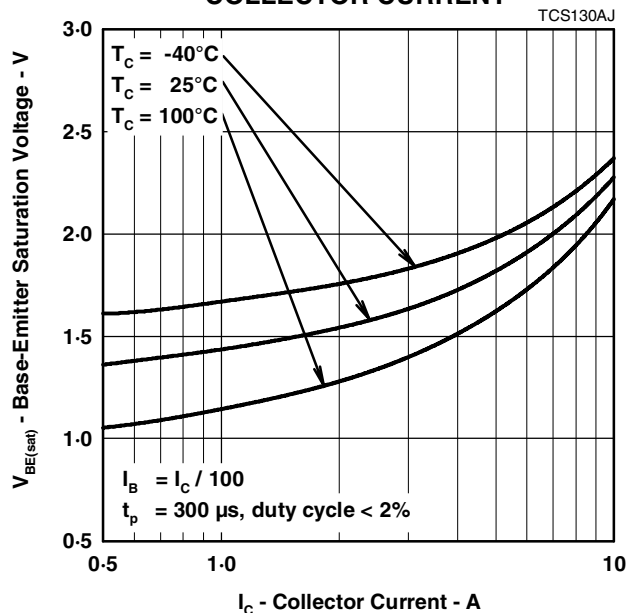


Figure 3.

PRODUCT INFORMATION

THERMAL INFORMATION

**MAXIMUM POWER DISSIPATION
vs
CASE TEMPERATURE**

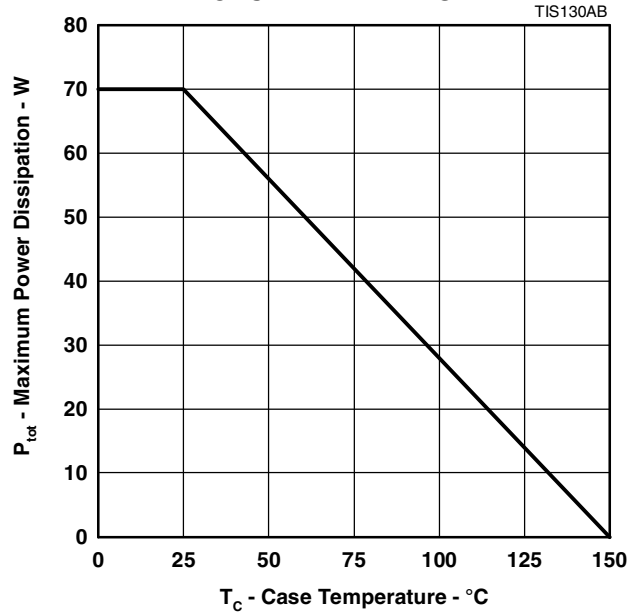


Figure 4.

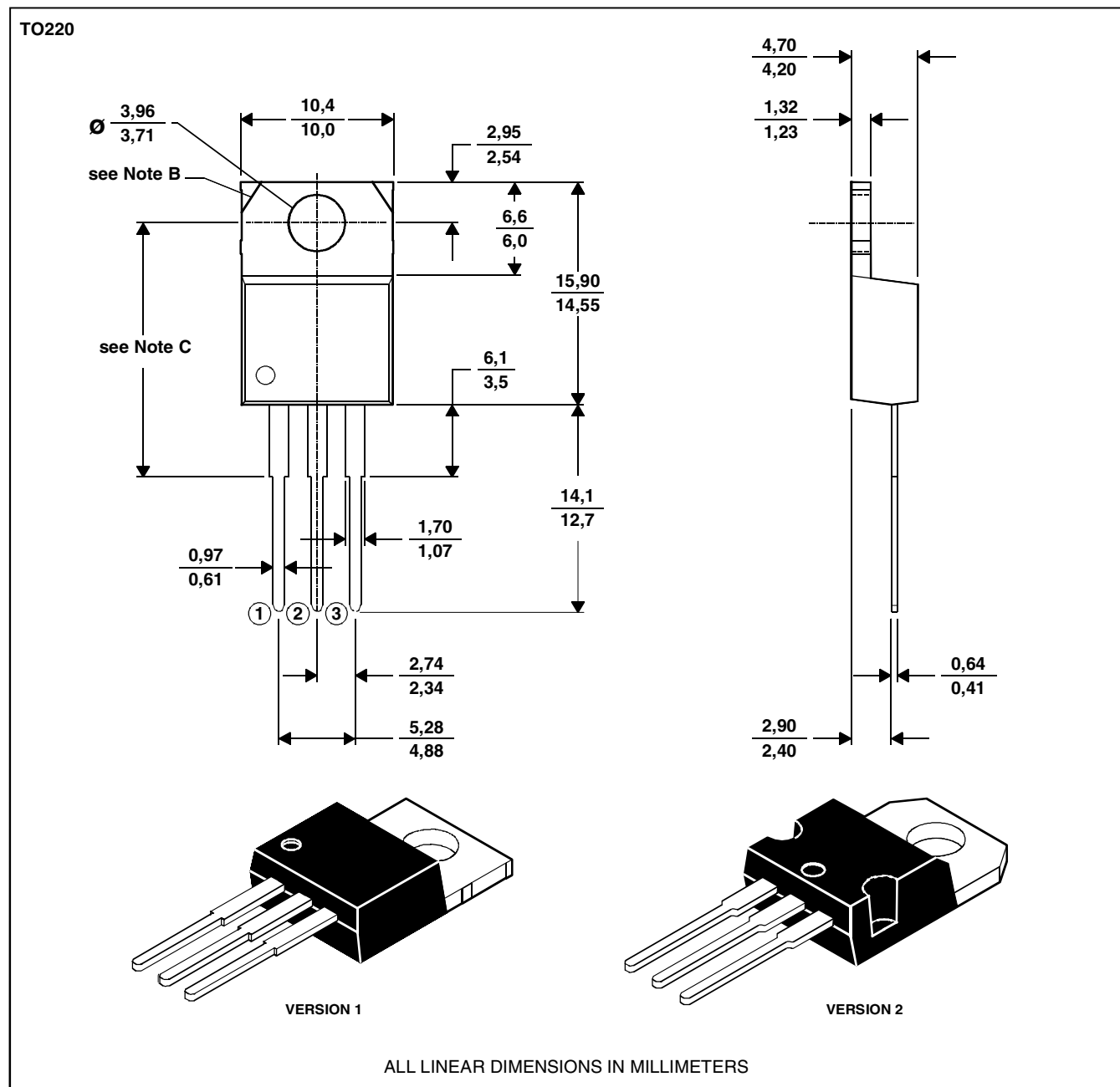
PRODUCT INFORMATION

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.
 B. Mounting tab corner profile according to package version.
 C. Typical fixing hole centre stand off height according to package version.
 Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

PRODUCT INFORMATION

AUGUST 1993 - REVISED SEPTEMBER 2002
 Specifications are subject to change without notice.